



Conceptual Design for SR/SP

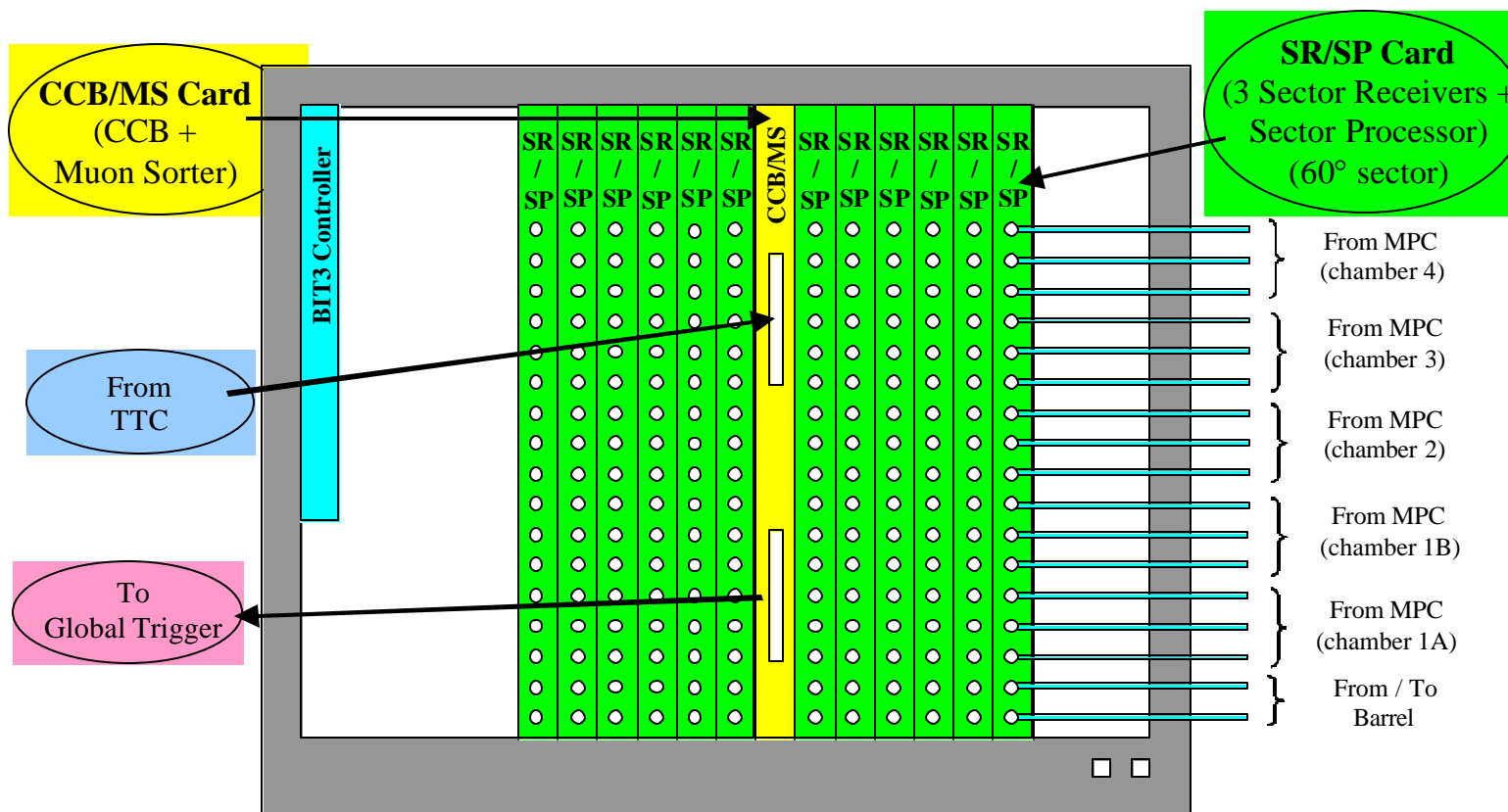
Topics:

- **Board Layout**
- **Bit counts and data serialization**
- **Memory architecture**
- **SP-in-a-chip**
- **Backplane**
- **DAQ interface**
- **Manpower**
- **Software limitations**



Possible Single Crate Solution

Track-Finder crate (1.6 Gbits/s optical links)



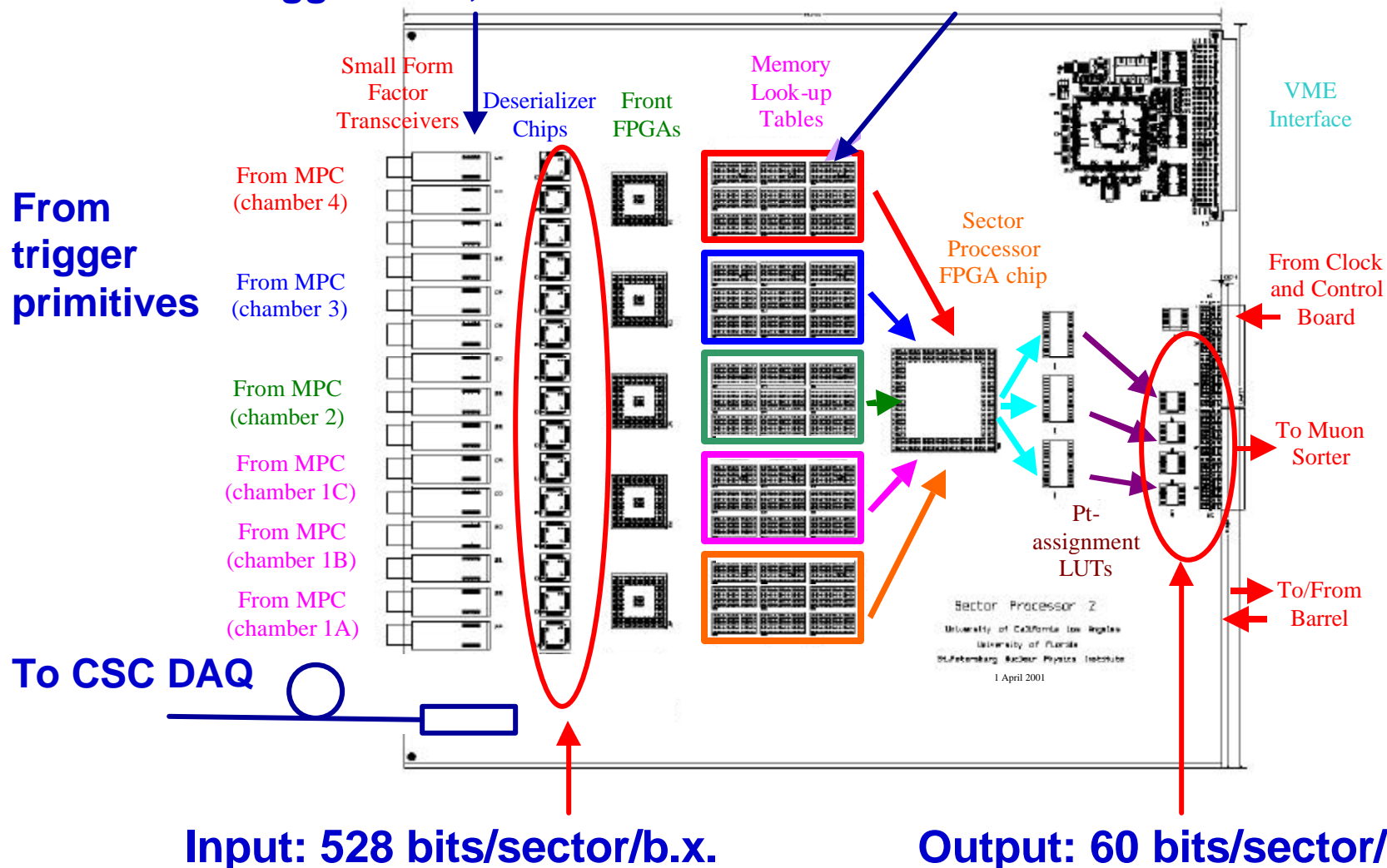
- **Total latency: ~ 20Bx (from input of SR/SP card to output of CCB/MS card)**
- **Power consumption: ~ 500W per crate**
- **15 optical connections per SR/SP card**
- **Custom backplane for SR/SPs < > CCB/MS connection**



Merged SR/SP

15 trigger links, 1 DAQ

51 or 27 SRAM





Bi-Directional Optical Links

Since we have both transmitters and receivers in the optical connection, this allows the option to send data as well as receive

→ Makes testing much easier (1 board sends data to other)



SR/SP Inputs

→ Muon Port Cards deliver 15 track stubs each BX via optical

Sent on first frame

Signal	Bits / stub	Bits / 3 stubs (1 MPC)	Bits / 15 stubs (ME1–ME4)	Description
½ Strip *	8	24	120	½ strip label
CLCT pattern *	4	12	75	Pattern number without 4/6, 5/6, 6/6
L/R bend *	1	3	15	Sign bit for pattern
Quality *	3	9	45	Computed by TMB
Wire group	7	21	105	Wire group label
Accelerator m	1	3	15	Straight wire pattern
CSC i.d.	4	12	60	Chamber label in subsector
BXN	2	6	30	2 LSB of BXN
Valid pattern	1	3	15	Must be set for above to apply
Spare	1	3	15	
Total:	32	96	480	(240 bits at 80 MHz)

Reduced from 5

Added

→ DT Track-Finder delivers 2 track stubs each BX via LVDS

Signal	Bits / stub	Bits / 2 stubs (MB1: 60°)	Description
f	12	24	Azimuth coordinate
f _b	5	10	φ bend angle
Quality	3	6	Computed by TMB
BXN	2	4	2 LSB of BXN
Synch/Calib	1	2	DT Special Mode
Muon Flag	1	2	2 nd muon of previous BX
Total:	24	48	



SR/SP Outputs

→ 6 track stubs are delivered to DT Track-Finder each BX via LVDS
 (can we multiplex at 80 MHz to save connector space?)

Signal	Bits / stub	Bits / 2 stubs (ME1: 20°)	Bits / 6 stubs (ME1: 60°)	Bits / 6 stubs @ 80 MHz	Description
f	12	24	72	36	Azimuth coordinate
h	1	2	6	3	DT/CSC region flag
Quality	3	6	18	9	Computed by TMB
BXN	–	2	6	3	2 LSB of BXN
	16	34	102	51	Total

→ 3 muons per SP are delivered to Muon Sorter via GTLP backplane

Signal	Bits / m	Bits / 3 m (1 SP)	Bits / 36 m (12 SP)	Description
f	5	15	180	Azimuth coordinate
h	5	15	180	Pseudorapidity
<u>Rank</u> *	7	21	252	5 bits p_T + 2 bits quality
Sign *	1	3	36	
BXN *	–	2	24	2 LSB of BXN
Error *	–	1	12	
Spare *	1	3	12	
Total:	19	60	720	(360 bits at 80 MHz)

Sent on first frame



Added, quality?





SR/SP Internal Dataflow

→ Data delivered from SR to SP

Signal	Bits / stub	Bits / 6 stubs (ME1)	Bits / 15 stubs (ME1–ME4)	Description
f	12	72	180	Azimuth coordinate
f _b	5	30	75	φ bend angle
h	6	36	90	Pseudorapidity
Accelerator m	1	6	15	η bend angle
Front/Rear *	1	6	6	ME1 chamber stagger
CSC ghost *	–	4	4	2 stubs in same ME1 CSC
Quality	3	18	45	Computed by TMB
Total:	28	172	415	(sent at 80 MHz)

ME1
only

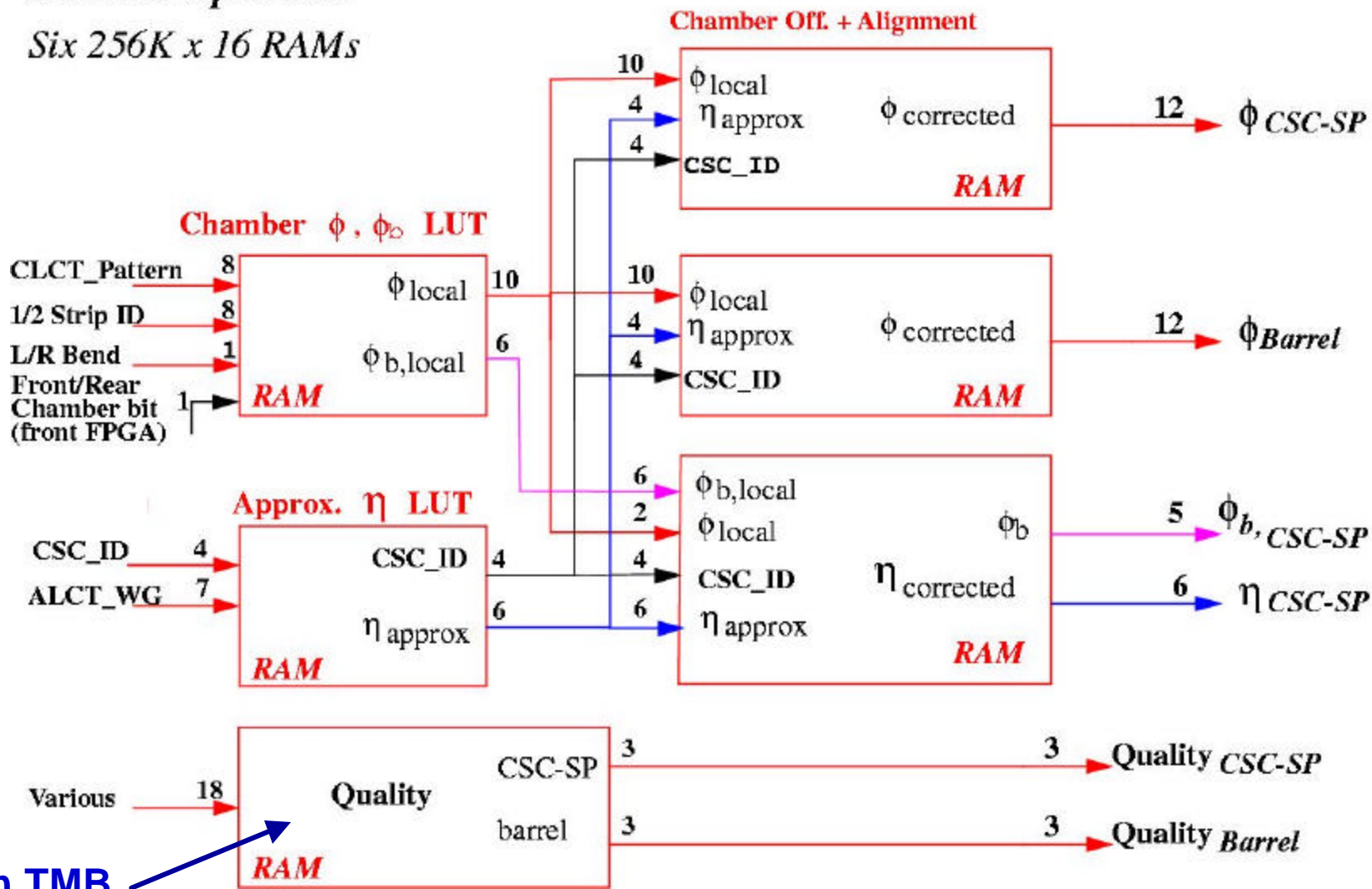
226 if stubs multiplexed



Old SR Memory Scheme

SR Look-Up Tables

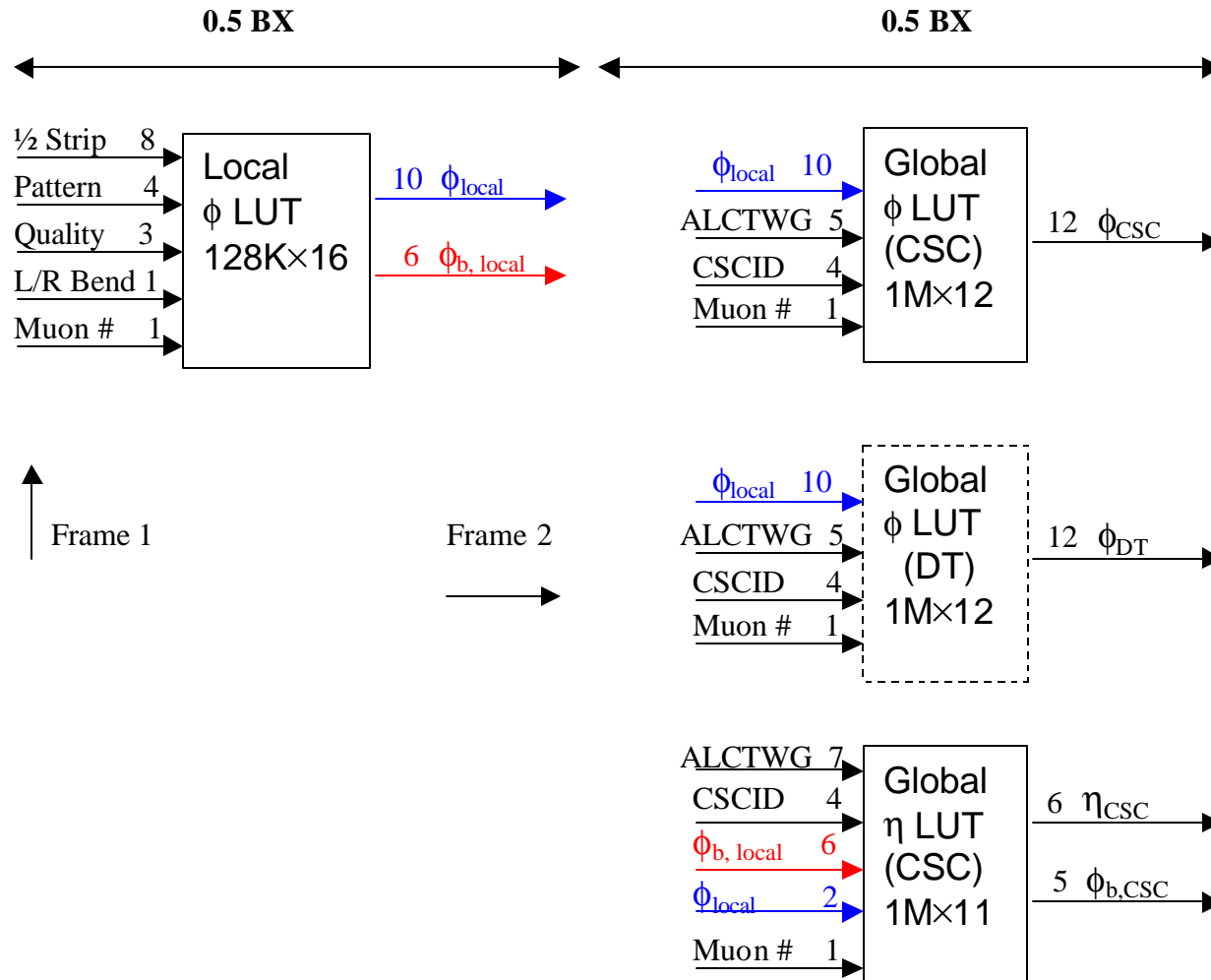
Six 256K x 16 RAMs



Now in TMB



New SR Memory Scheme





Discussion of SR Memory (1)

Data Frames:

- Data arrives off links @ 80 MHz
- The proposed framing scheme implies no latency loss
 - First LUT operates on first frame only (but must reduce CLCT pattern label by 1 bit)
 - Can send 2 muons through one memory set with only 0.5 BX latency penalty to reduce chip count
- This frame definition must be applied in the **TMB** where the data is generated and first serialized (i.e. before MPC) to avoid latency penalty

Memories:

- LUT for DT only applies to ME1
- Chip count is 4 or 3 per stub, down from 6 originally
- Increased memory size to 1M (okay for synch. SRAM)
- “Muon #” only applies if more than one stub in a BX is sent through same memory



Discussion of SR Memory (2)

One memory set per stub:

- $6 \times 4 + 9 \times 3 = 51$ chips
- 1 BX latency
- 415 signals to SP

Multiplex stubs at 80 MHz:

- $3 \times 4 + 5 \times 3 = 27$ chips
- 1.5 BX latency
- 226 signals to SP

First SR had 36 chips and 1 BX latency

Memory choices:

- Current synch SRAM clocked at 160 MHz (tested) →
- next generation synch SRAM clocked at 80 MHz
- asynch SRAM (but must remove 2 bits in final LUTs)



Pipelined Memory Tests

Developed small evaluation board to test two pipelined memories in series

- **Samsung 1M x 18 synch. SRAM (K7A161800M)**
- **Include scheme to multiplex two muon stubs through same memory set @ 80 MHz**

Tested chips up to 150 MHz and encountered no errors with random number inputs

- **Specified maximum frequency is 180 MHz**

Low power

- **~1W per memory at 150 MHz**

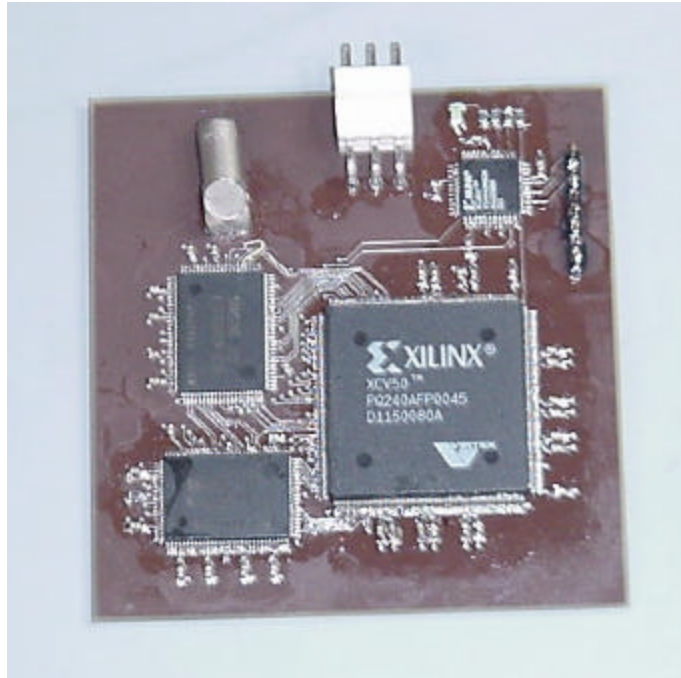
Latency determination

- **2 clocks per memory (4 clocks for two in series)**
- **Next generation will require just one clock**

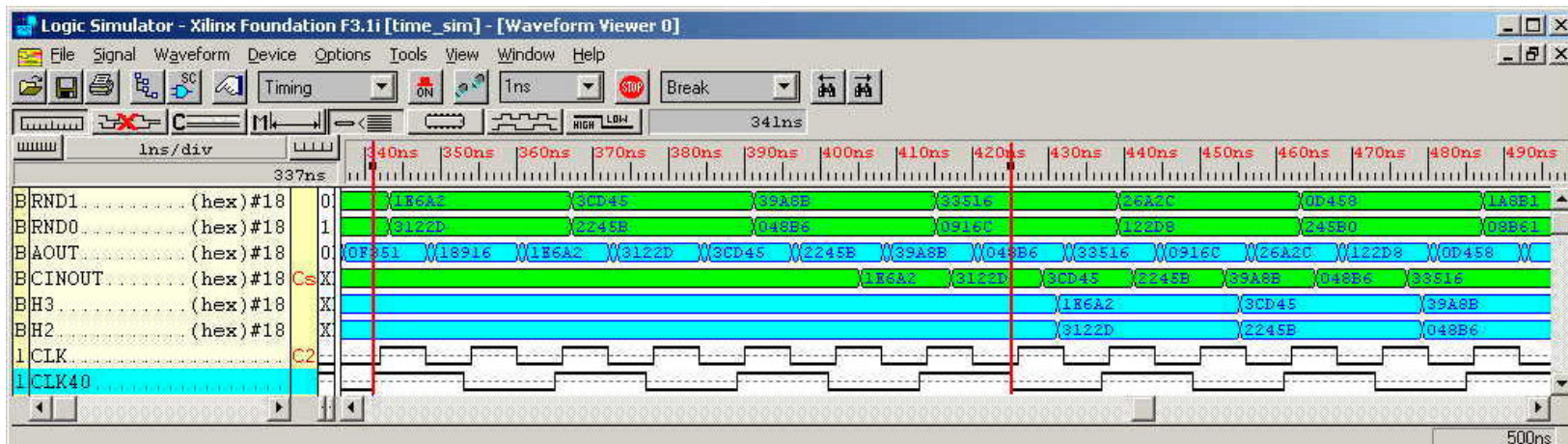


SR Memory Prototype

Tested hardware →

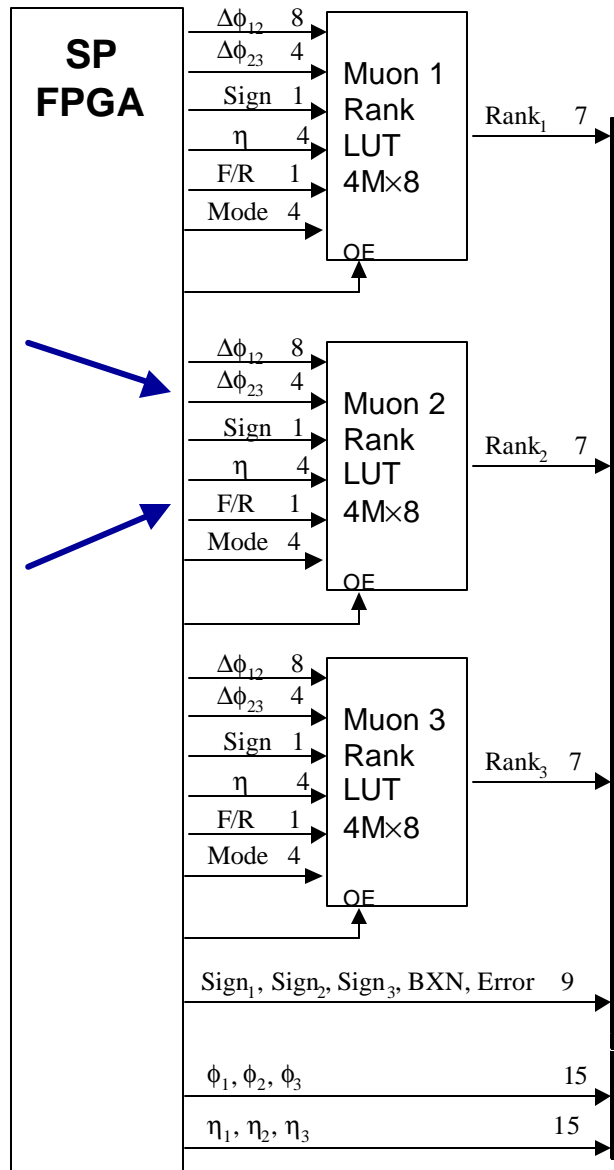


Simulation illustrating clocking of board





SP Memory Scheme



- Must serialize to fit data on backplane
- No latency penalty for serialization if Rank sent first to Muon Sorter
- SP FPGA contains tri-state buffers and generates enable for memories

Df_{23} could be replaced by f_b

Added F/R bit to improve P_T resolution

Frame 1

30 GTLP backplane

80 MHz

Frame 2



SP in a Chip Study

Feasibility study was performed to fit all Sector Processor logic into one FPGA

- Merged all separate schematics from current SP prototype into one project (17 FPGAs)
 - Transformed large Track Assembler LUTs into a Verilog algorithm for FPGA
 - Utilized 63% of the resources of a Xilinx Virtex-E (XCV1600EFG680-8)
 - **Must understand how much f_b logic adds**
 - Simulation shows that the latency of the SP logic is **11 BX** at a maximum frequency of **41 MHz**
 - **Add 1 BX for final P_T Assignment LUT**
 - **Compare to 15 BX of current SP prototype \Rightarrow save 3 BX**
 - ChannelLink between SR and SP removed (**save 4 BX more**)
 - SP Chip I/O:
 - **415 (or 226) CSC + 48 DT input bits**
 - **~135 output bits + control signals**
- \Rightarrow ~600 max I/O**



Backplane Development

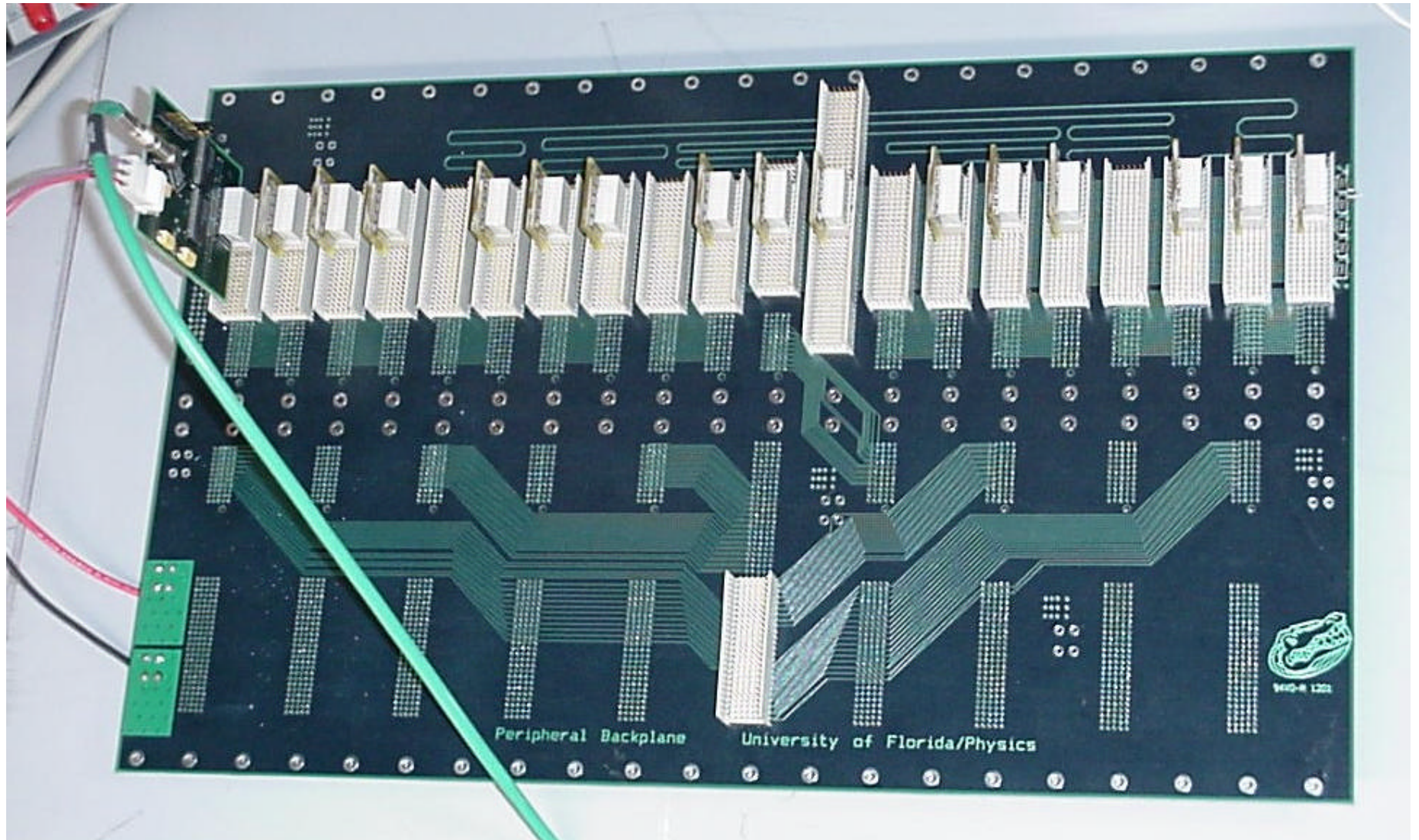
Next generation backplane technology will be GTLP

- No differential signals (fewer traces)
- We first tested a small prototype backplane with GTLP signals
 - It works: tested drivers from Fairchild, and Xilinx Virtex I/O

- We have now tested a full 21 slot custom VME backplane for use in the CSC front-end peripheral crate
 - Includes 40 MHz bussed signals and 80 MHz point-to-point
 - Highest density is ~660 signals into Muon Port Card (vs. ~720 signals into CSC Muon Sorter in CSC TF crate) multiplexed at 80 MHz
 - Have tested bussed signals with backplane fully loaded



Prototype Peripheral Crate Backplane





CSC TF DAQ Bandwidth

Send input of SR and output of SP to DAQ stream for diagnostics

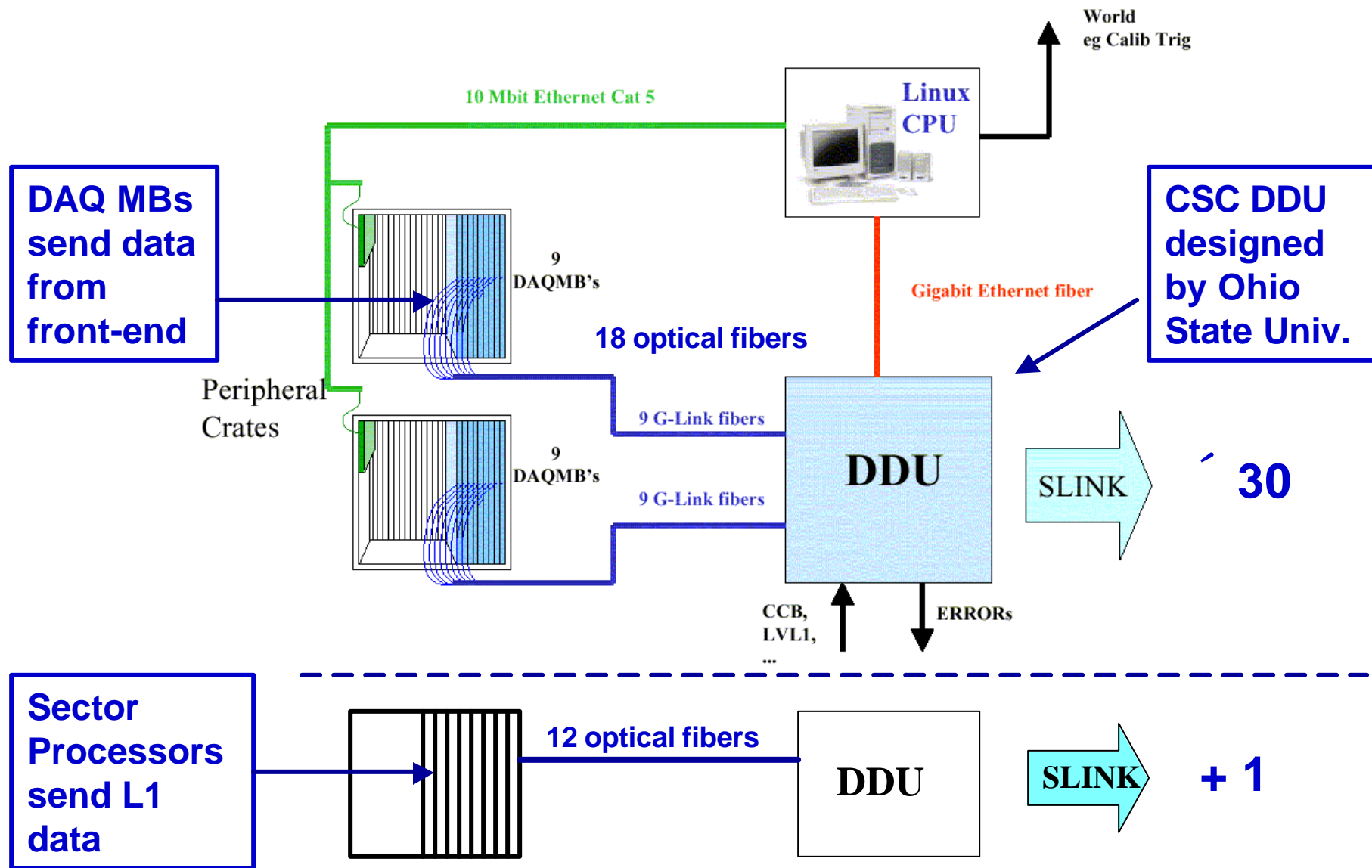
- Send ~600 bits (80B) per L1A per SR/SP
- 12 SR/SP send **1kB per L1A**
- 100 kHz L1A rate \Rightarrow **100 MB/s**
- One S-LINK64 handles 200 MB/s

- Note that trigger data is expected to be sparse, so this bandwidth is an **upper limit** and should be compressed

- CSC Track-Finder DAQ acts as additional DDU for CSC system (plan to use existing DDU design by OSU)
 - OSU may use new HP serializer in place of TI for compatibility with Gbit ethernet
 - They should have results from an evaluation board within a month



Mirror CSC DAQ Path





Manpower

University of Florida

- D.A. – PI
- Alex Madorsky – lead engineer
- Bobby Scurlock – graduate student
 - Trigger simulations
 - SP firmware/software tuning, crate tests

PNPI

- Victor Golovtsov – PI
- Lev Uvarov – design engineer
 - Replaces Boris
 - Extensive experience on D0 (muon readout), E781, E761

UCLA

- R.C. – PI
- Jason Mumford – graduate student
- Slava – postdoc
 - Both maintain trigger primitive and SR software



Software Limitations

CLCT patterns and pattern number

- No f_b from SR
- f_b not used for extrapolation in SP
 - Might reduce backgrounds
 - Logic size not counted in SP chip study
- f_b could improve P_T assignment
- Improved f precision results from using 6 layers vs. 1
 - Could improve P_T resolution

Track-Finder algorithms

- Bunch Crossing Analyzer not implemented or tested
- New Verilog Track Assembler needs simulation
- Miscellaneous cuts need tuning: h , quality, ...
 - Should improve low P_T rejection

Validation against current HW designs

- Need closer link to hardware LUTs and algorithms
- Improve maintenance of design to shorten debug time for next prototypes





Design Maintenance

Will overhaul some of the SP software/firmware to facilitate changes to both

- Have SW algorithms match Verilog better
- Have SW read same HW LUTs (it already generates them)

Plan to test next SP design even before construction!

- Add utilities to write ORCA data into Xilinx simulator format and to compare simulator output to ORCA
- Gives us a head start on validating logic design
- Will allow us to focus on HW debugging rather than SW debugging when testing the next prototype